TI Precision Labs – Ethernet

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Crystal oscillator architecture for TI PHYs

Designator	Description
XTAL	AT cut, 25 MHz crystal
CL1, CL2	Load capacitors
R1	Current limiting resistor
Rfb	Feedback resistor







Important crystal parameters to consider:

- Frequency tolerance
- Frequency stability
- Load capacitance
- ESR
- Drive level

Example Crystal Specifications

Parameters	Min	Тур	Max	Units
Frequency Range	24.000 0		52.000 0	MHz
Operating Temperature Range	-40		+125	°C
Frequency Tolerance @ +25°C	-10		+10	ppm
Frequency Stability over Operating Temperature	-10		+10	ppm
Equivalent series resistance (ESR)		< 80	100	Ω
Load capacitance (CL)		4.0		pF
Drive Level (DL)		10	100	μW
Aging (1 year)	-2		+2	ppm



Load capacitors selection



CL1 & CL2 ≠ load capacitance (CL) specified in XTAL datasheet



Current limiting resistor selection

- 1. Start with the first order approximation for R1: $R1 = \frac{1}{2\pi \times 25 \text{ MHz} \times \text{CL2}}$
- 2. Measure $I_{Y1, RMS}$ and determine if the crystal drive level meets the crystal specifications $DL_{max} \ge I_{XTAL, RMS}^2 \times ESR$
- 3. Increase value of R1 if calculated crystal drive level is not within crystal specifications
- 4. Calculate $V_{CL1, pk-pk}$ and ensure it satisfies V_{ih} requirements of PHY's XI pin $V_{CL1, pk-pk} = I_{XTAL, RMS} \times \sqrt{2} \times |Z_{CL1}|$

NOTE: 500 μW or higher crystals may not require a current limiting resistor





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- 1. The IEEE 802.3 standard suggests frequency accuracy of +/- 100 ppm what does this include?
 - a) Frequency tolerance
 - b) Frequency drift due to aging
 - c) Frequency stability over temperature
 - d) All of the above
- 2. Ceq decreases when _____
 - a) pin capacitance of XI pin increases
 - b) PCB traces from PHY to XTAL are thicker
 - c) XTAL is moved closer to the PHY, shortening traces
 - d) CL1 and CL2 values are both doubled



- 3. Which of these can cause the drive level to exceed the crystal datasheet specification?
 - a) Decreasing R1
 - b) Decreasing CL2
 - c) Increasing CL1
 - d) Decreasing CL1



Solutions



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